

成品图

NOTES:

¹.FINISH:

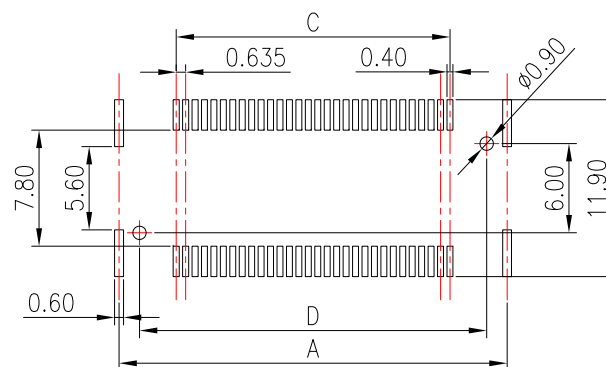
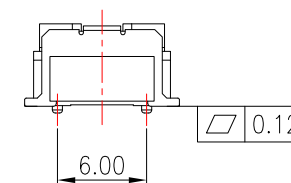
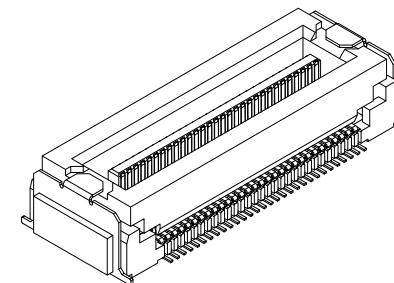
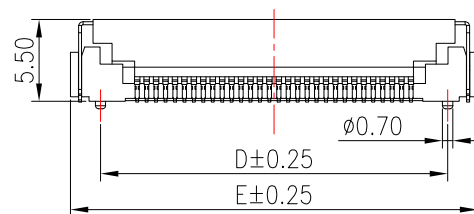
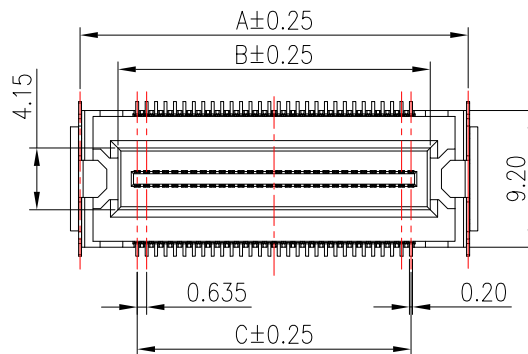
- 1.1 HOUSING: LCP BLACK,UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u"MIN NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS,80u" MIN MATTE TIN PLATED OVER 50u" MIN NICKEL UNDERPLATED OVERALL.
2. ELECTRICAL:
 - 2.1 CURRENT RATING: 5A FOR VBUS PIN;
 - 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 200V AC/MINUTE.
 - 2.3 CONTACT RESISTANCE: 100mΩ MAX.
 - 2.4 INSULATION RESISTANCE: 250V DC/0.1S/100MΩ
- 3.SALT SPRAY TEST:
 - 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C, TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.Max Processing Temp:265°C Seconds 40S
- 5.ORDER INFORMATION:

66B1-F XXX XX 055 R 01

Pin 数码	端子电镀:	塑胶高度:	包装方式:
SEE TABLE	G0=Gold Flash(全金)	055=5.50mm	R=TAPE REEL
030=2x15PIN	G1=1u" Gold		
050=2x25PIN	G2=3u" Gold		
.....	G3=5u" Gold		
	G4=10u" Gold		
	G5=15u" Gold		
	G6=30u" Gold		

TABLE 1:

No. OF PIN	A	B	C	D	E
20=2x10PIN	13.400	8.300	5.715	10.650	14.700
30=2x15PIN	16.575	11.475	8.890	13.825	17.875
50=2x25PIN	22.925	17.825	15.240	20.175	24.225
60=2x30PIN	26.100	21.000	18.415	23.350	27.400
80=2x40PIN	32.450	27.350	24.765	29.700	33.750
100=2x50PIN	38.800	33.700	31.115	36.050	40.100
120=2x60PIN	45.150	40.050	37.465	42.400	46.450



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF ± 0.05 (PCB T=1.00mm)

					OPERATION		DRAW		WLY		2020.10.23		 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X	±0.40	DESIGN		Jensen		2020.10.23					
					X.XX	±0.25	CHECK		Jack		2020.10.23		SIZE	A4	PART NO.	66B1-FXXXXX055R01
					X.XXX	±0.15										
AO		NEW	_____	_____	Angle	±3°	APPROVE		Andy		2020.10.23		SHEET	1/1	TITLE:	0.635PH 浮动BTB母座 直立式SMT TYPE
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.		DRAW NO.	SP-348	

客户图

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4.Max Processing Temp:265°C Seconds 40S

5.ORDER INFORMATION:

66B1-M XXX XX XXX R 01

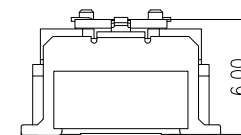
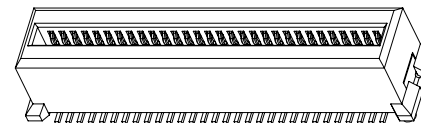
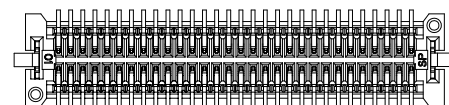
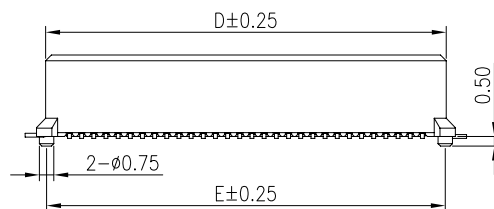
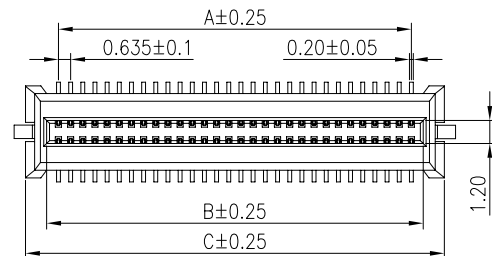
Pin 数码 SEE TABLE	端子电镀: G0=Gold Flash(全金) G1=1u" Gold G2=3u" Gold G3=5u" Gold G4=10u" Gold G5=15u" Gold G6=30u" Gold	塑胶高度: 042=4.25mm	包装方式: R=TAPE REEL
030=2x15PIN			
050=2x25PIN			
.....			

TABLE1:

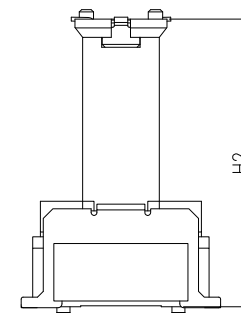
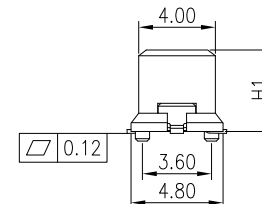
No. OF PIN	A	B	C	D	E
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30=2x15PIN	8.890	10.125	12.325	11.375	11.275
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60=2x30PIN	18.415	19.650	21.850	20.900	20.800
80=2x40PIN	24.765	26.000	28.200	27.250	27.150
100=2x50PIN	31.115	32.350	34.550	33.600	33.500
120=2x60PIN	37.465	38.700	40.900	39.950	39.850

TABLE2:

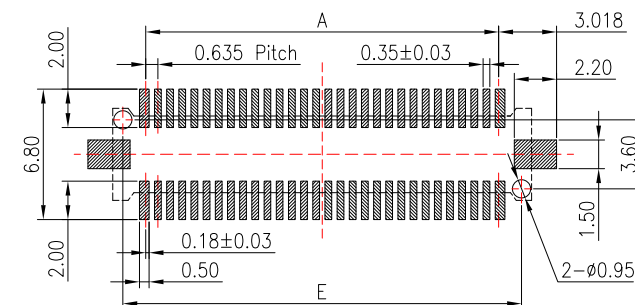
塑胶高度 (H1)	装配合高 (H2)
4.25	6.0
6.25	8.0
8.25	10.0
13.25	15.0



公母座装配高6.0mm



公母座装配高8~15.0mm



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05(PCB T=1.00mm)

					OPERATION		DRAW		WLY		2020.10.23		SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X	±0.40	DESIGN		Jensen		2020.10.23					
					X.XX	±0.25	CHECK		Jack		2020.10.23		SIZE	A4	PART NO.	66B1-MXXXXXXXR01
A0		NEW		_____	X.XXX	±0.15	APPROVE		Andy		2020.10.23		SHEET	1/1	TITLE:	0.635PH 浮动BTB公头 直立式SMT TYPE
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.		DRAW NO.	SP-349	